

ABSTRACT

Disclosed in one embodiment of the present invention is an electroplating apparatus and an electroplating method. The electroplating apparatus comprises a plurality of paddles arranged in parallel. The paddles move in a direction parallel to a substrate, and are used to stir electroplating solution. Within one cycle, the paddles perform reciprocating motion at a set stroke, and the turning points of the reciprocating motion are related to the width of the paddles and the narrowest width of a gap between adjacent paddles. According to the present invention, by designing the size and movement mode of the paddles, the accumulated time in which each corresponding point on the substrate is blocked by the paddles is equal, so that the received quantity of electricity is equal, and thus the consistency of an electroplating height is further improved.